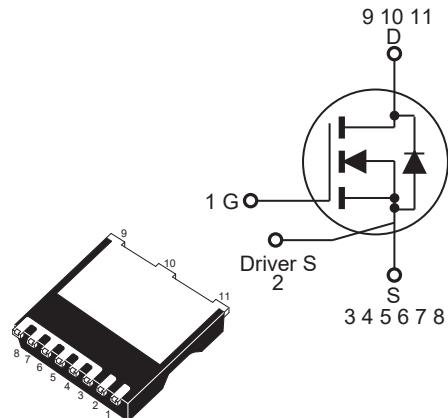
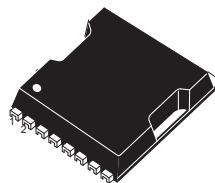


## N-Channel Enhancement Mode Field Effect Transistor With Fast Body Diode

### FEATURES

- 700V@ $T_J$  max, 52A,  $R_{DS(ON)} = 58m\Omega$  @ $V_{GS} = 10V$
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Pb-free lead plating ;RoHS compliant.
- Halogen Free.
- Fast reverse recovery time( $T_{rr}$ ).
- TOLL package.



### Applications

- EV Charging.
- Telecom.
- Server.
- Solar.
- SMPS.

### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous@ $T_C = 25^\circ C$ @ $T_C = 100^\circ C$	$I_D$	52 32	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	208	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above 25°C	$P_D$	390 3.1	W W/°C
Single Pulsed Avalanche Energy <sup>f</sup>	$E_{AS}$	380	mJ
Single Pulsed Avalanche Current <sup>f</sup>	$I_{AS}$	4.5	A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	0.32	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	60	°C/W



# CEL52N65SF

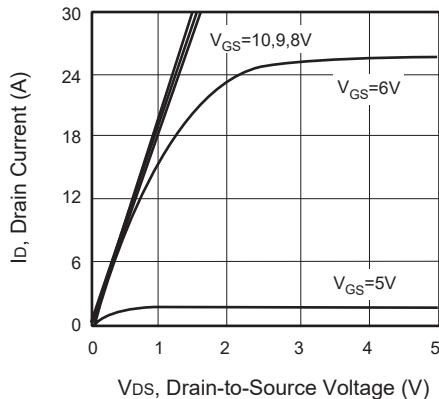
## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$		5		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		49	58	$\text{m}\Omega$
Gate Input Resistance	$R_g$	f=1MHz,open Drain		3.4		$\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2300		pF
Output Capacitance	$C_{\text{oss}}$			120		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			10		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 520\text{V}, I_D = 10\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 10\Omega$		52		ns
Turn-On Rise Time	$t_r$			23		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			176		ns
Turn-Off Fall Time	$t_f$			9		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 520\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		92		nC
Gate-Source Charge	$Q_{\text{gs}}$			21		nC
Gate-Drain Charge	$Q_{\text{gd}}$			37		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				46	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$			1.5	V
Reverse Recovery Time	$T_{\text{rr}}$	$I_F = 20\text{A}, \text{di/dt} = 100\text{A/us}$		183		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			1.2		$\mu\text{C}$
Peak Reverse Recovery Current	$I_{\text{rr}}$			12		A
Reverse diode dv/dt ruggedness, $V_{\text{DS}} = 0\dots480\text{V}, I_{\text{SD}} \leq I_D$	dv/dt	$I_{\text{DR}} = 10\text{A}, V_{\text{GS}} = 0\text{V}, V_{\text{DD}} = 400\text{V}$		100		V/ns
MOSFET dv/dt ruggedness, $V_{\text{DS}} = 0\dots480\text{V}$				100		V/ns

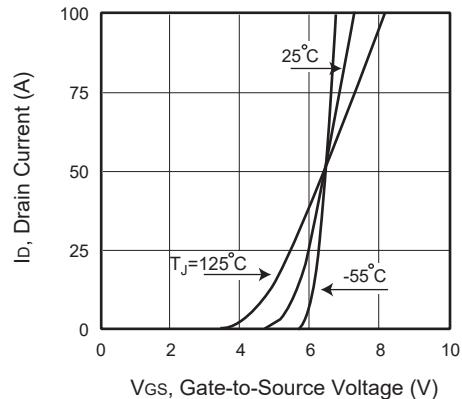
Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.

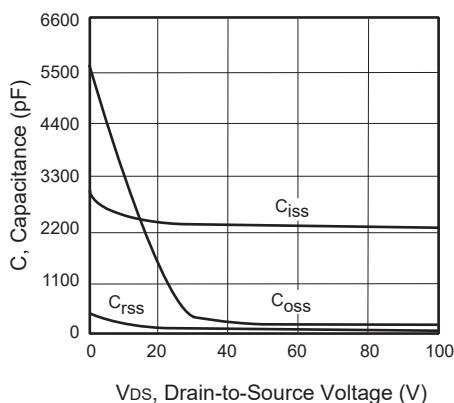
d.L = 37.5mH,  $I_{AS} = 4.5\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .



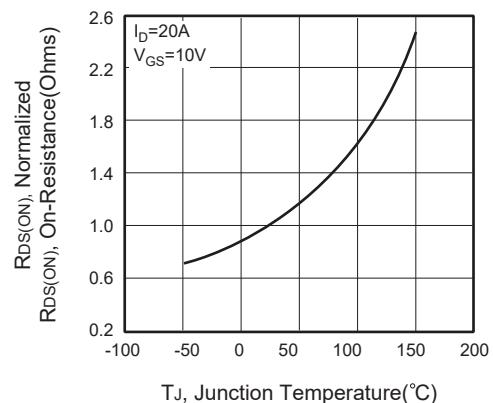
**Figure 1. Output Characteristics**



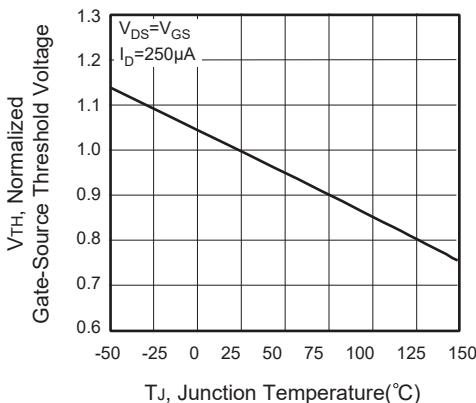
**Figure 2. Transfer Characteristics**



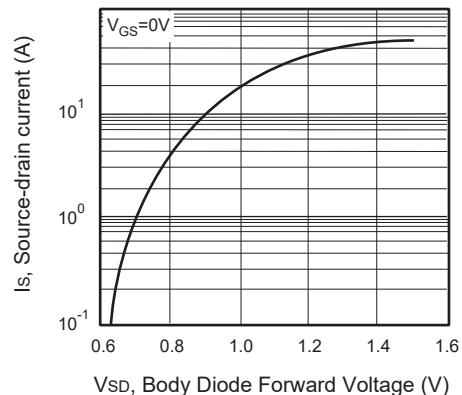
**Figure 3. Capacitance**



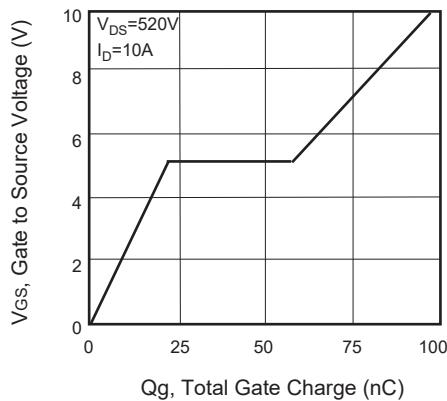
**Figure 4. On-Resistance Variation with Temperature**



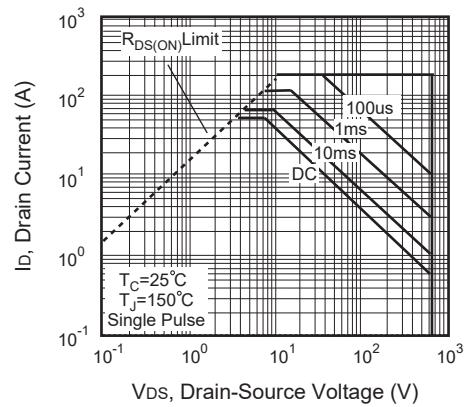
**Figure 5. Gate Threshold Variation with Temperature**



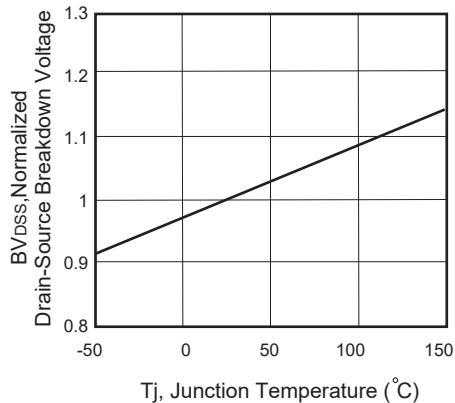
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



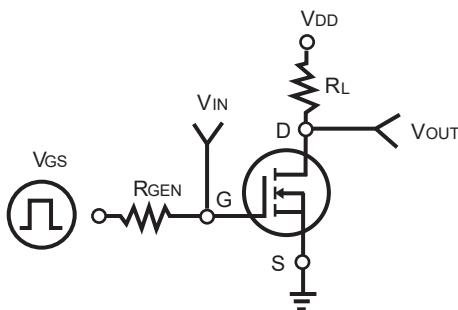
**Figure 7. Gate Charge**



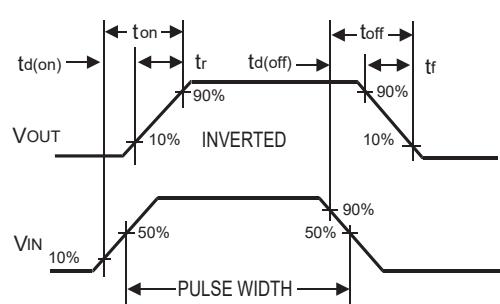
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**

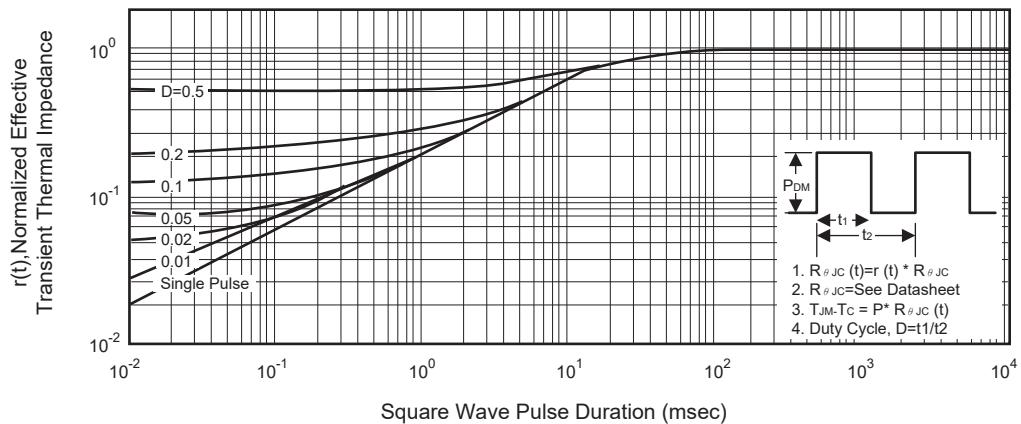
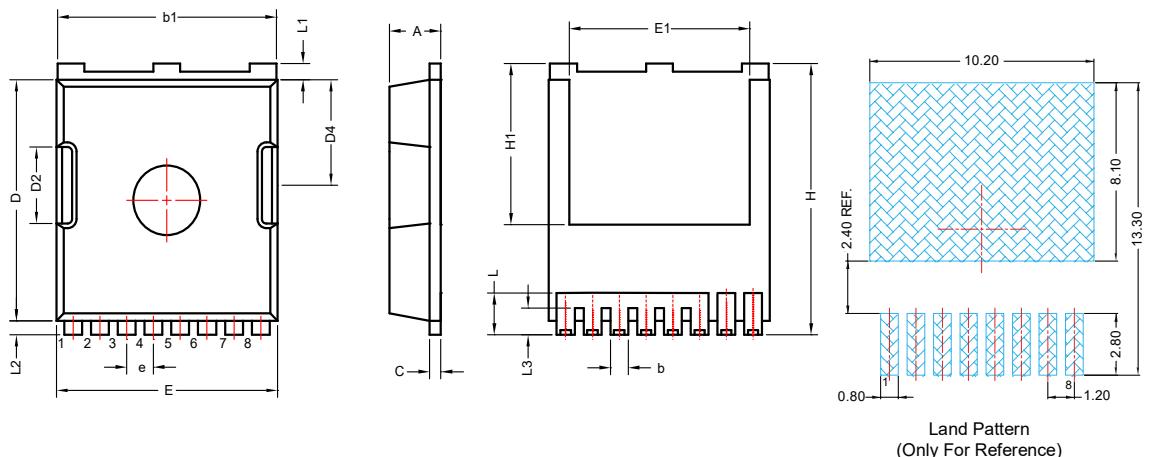


Figure 12. Normalized Thermal Transient Impedance Curve



# CEL52N65SF

TOLL 產品外觀尺寸圖 (Product Outline Dimension)



Land Pattern  
(Only For Reference)

SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.150	2.450	0.085	0.096
b	0.700	0.900	0.028	0.035
b1	9.650	9.950	0.380	0.392
c	0.400	0.600	0.016	0.024
D	10.180	10.580	0.401	0.417
D2	3.150	3.450	0.124	0.136
D4	4.400	4.700	0.173	0.185
E	9.700	10.100	0.382	0.398
E1	7.950	8.250	0.313	0.325
e	1.20BSC		0.047BSC	
H	11.480	11.880	0.452	0.468
H1	6.800	7.100	0.268	0.280
L	1.500	2.100	0.059	0.083
L1	0.500	0.900	0.020	0.035
L2	0.500	0.720	0.020	0.028
L3	1.000	1.300	0.039	0.051